

Abstract

A chemical mechanical polishing pad (200) that includes a polishing layer (204) having a polishing region (208) and containing a plurality of grooves (212) extending at least partially into the polishing region. During polishing, the grooves contain a slurry (236) that facilitates polishing. Each groove includes a plurality of mixing structures (220) configured to cause mixing of slurry located in a lower portion (240) of the groove with slurry located in the upper portion (244) of the groove.